

L Number	Hits	Search Text	DB	Time stamp
-	54	system and substrate and (print\$6 adj circuit adj board 'PCB' aluminum near2 frame grid near2 array) and ((polymer thermoplastic thermoset photo\$2resist DNQ\$4 diazonaphthoquinone novolac epoxy polyamide) and (magnetic ferro\$2magnetic titanate barium adj strontium adj titanate strontium adj tantalum adj oxide perovskite iron cobalt nickel)) near7 (interconnect\$4 coupl\$4 packag\$4) and (particle grain) near2 (size diameter 'nm' micron) and (acicular flake (length width aspect diameter) near2 ratio)	USPAT; US-PGPUB	2004/11/05 11:15
-	20	system and substrate and (print\$6 adj circuit adj board 'PCB' aluminum near2 frame grid near2 array) and ((polymer thermoplastic thermoset photo\$2resist DNQ\$4 diazonaphthoquinone novolac epoxy polyamide) and (titanate barium adj strontium adj titanate strontium adj tantalum adj oxide perovskite )) near5 particle and (interconnect\$4 coupl\$4 packag\$4)	USPAT; US-PGPUB	2004/11/05 11:15
-	91	system and substrate near5 (interconnect\$4 coupl\$4 packag\$4) and (print\$6 adj circuit adj board 'PCB' aluminum near2 frame grid near2 array) and (polymer thermoplastic thermoset photo\$2resist DNQ\$4 diazonaphthoquinone novolac epoxy polyamide) and (magnetic ferro\$2magnetic titanate barium adj strontium adj titanate strontium adj tantalum adj oxide perovskite iron cobalt nickel ) near5 (particle flake) and (particle grain) near2 (size diameter 'nm' micron ultra\$2fine) and (acicular flake (length width aspect diameter) near2 ratio)	USPAT; US-PGPUB	2004/11/05 11:15
-	4	system and substrate with (interconnect\$4 coupl\$4 packag\$4) with component and (print\$6 adj circuit adj board 'PCB' aluminum near2 frame grid near2 array) and (polymer thermoplastic thermoset photo\$2resist DNQ\$4 diazonaphthoquinone novolac epoxy polyamide) and (titanate barium adj strontium adj titanate strontium adj tantalum adj oxide perovskite ) near5 (particle flake)	USPAT; US-PGPUB	2004/11/05 11:15
-	5	screen adj pad and (printed adj circuit adj board 'PCB' grid near5 array aluminum near2 frame) and (interconnect packaging magnetically near5 align\$3)	USPAT; US-PGPUB	2004/11/05 11:16
-	26	((polymer thermoplastic thermoset photo\$2resist DNQ\$4 diazonaphthoquinone novolac epoxy polyamide) and (magnetic ferro\$2magnetic titanate iron magnetite barium adj strontium adj titanate strontium adj tantalum adj oxide perovskite iron cobalt nickel 'fe' 'co' 'ni' ) and (particle powder fiber grain) near5 align\$4 near5 magnetic) and conductive near5 interconnect	USPAT; US-PGPUB	2004/11/05 11:16
-	20	( ((polymer thermoplastic thermoset polyamide epoxy photo\$2resist DNQ\$4 diazonaphthoquinone novolac) and (magnetic ferro\$2magnetic titanate iron magnetite perovskite)) and (particle powder fiber grain) near5 align\$4) and (conductive interconnect\$4 packag\$4)	EPO; JPO; DERWENT; IBM_TDB	2004/11/05 11:16
-	16	("5232661" "5536908" "5526978" "5545367" "5618189" "5846854" "09023049" "01052303").did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/11/05 12:46